



NOEL Technologies

WET-CHEMICAL ETCH TABLE TEMPLATE

Etch Chemistry	Films	E/R Per Minute ($\pm 10\%$)	Temperature Control
Pre-Mixed 7:1 BOE	Thermal Oxide	800A	22C - 24°C
Pre-Mixed 7:1 BOE	PECVD TEOS	1,500A	22C - 24°C
Pre-Mixed 7:1 BOE	PECVD Nitride	150A	22C - 24°C
Pre-Mixed 7:1 BOE	Titanium	2,000A	22C - 24°C
Pre-Mixed Chromium	Chrome	700A \pm 100A	22C - 24°C
Pre-Mixed ITO	Indium Tin Oxide	150A \pm 50A	22C - 24°C
KOH (32%)	Silicon (bulk)	8,000A	80C \pm 1°C
KOH (32%)	Polysilicon	5,000A	80C \pm 1°C
Pre-Mixed PolySilicon (40:1:2:20)	Polysilicon	5,000A	22C - 24°C
10:1 Hydrogen Peroxide/ Ammonium Hydroxide	TiN;W	120A	22C - 24°C
Pre-mixed Aluminum (16:1:1:2) Phosphoric:Nitric:Acidic:Water	Al, Al/Cu, Al/Si	(Etch-rate Is Dependant) On Temperature	30C - 55°C (Thickness Dependant)
TMAH (25%)	Silicon (Bulk)	"4,000A"	80C \pm 1°C